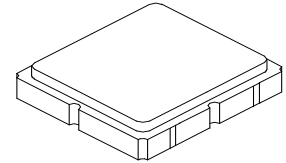


- Low-loss 1960 MHz Filter
- Complies with Directive 2002/95/EC (RoHS)



SF2215E

**1960 MHz
SAW Filter**



SM3030-6

Absolute Maximum Ratings

Rating	Value	Units
Input Power Level	+10	dBm
DC Voltage on any Non-ground Terminal	3	V
Operable Temperature Range	-45 to +125	°C
Operating Temperature Range	-20 to +75	°C
Storage Temperature Range in Tape and Reel	-40 to +85	°C
Maximum Soldering Profile, 5 cycles/10 seconds maximum	265	°C

Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	fC			1960.0		MHz
Insertion Loss, 1927.5 to 1992.5 MHz	IL			2.7	4.0	dB
Peak-to-Peak Amplitude Ripple, 1927.5 to 1992.5 MHz				1.3	2.5	dB
Input/Output Return Loss, 1927.5 to 1992.5 MHz			7.4	2.5		
Group Delay, 1927.5 to 1992.5 MHz				25		ns
Attenuation, Referenced to 0 dB:						dB
DC to 1740 MHz			20	31		
1740 to 1801 MHz			30	36		
1801 to 1880 MHz			20	41		
2040 to 2120 MHz			25	40		
2120 to 2500 MHz			31	38		
3700 to 4000 MHz			25	32		
Source Impedance	ZS			50		Ω
Load Impedance	ZL			50		Ω
Case Style	SM3030-6 3.0 x 3.0 mm Nominal Footprint					
Lid Symbolization (Y=year, WW=week, S=shift) dot=pin 1 indicator	951, <u>YWWS</u>					
Standard Reel Quantity	Reel Size 7 inch	500 Pieces/Reel				
	Reel Size 13 inch	3000 Pieces/Reel				

Electrical Connections

Connection	Terminals
Input	2
Output	5
Case Ground	All others

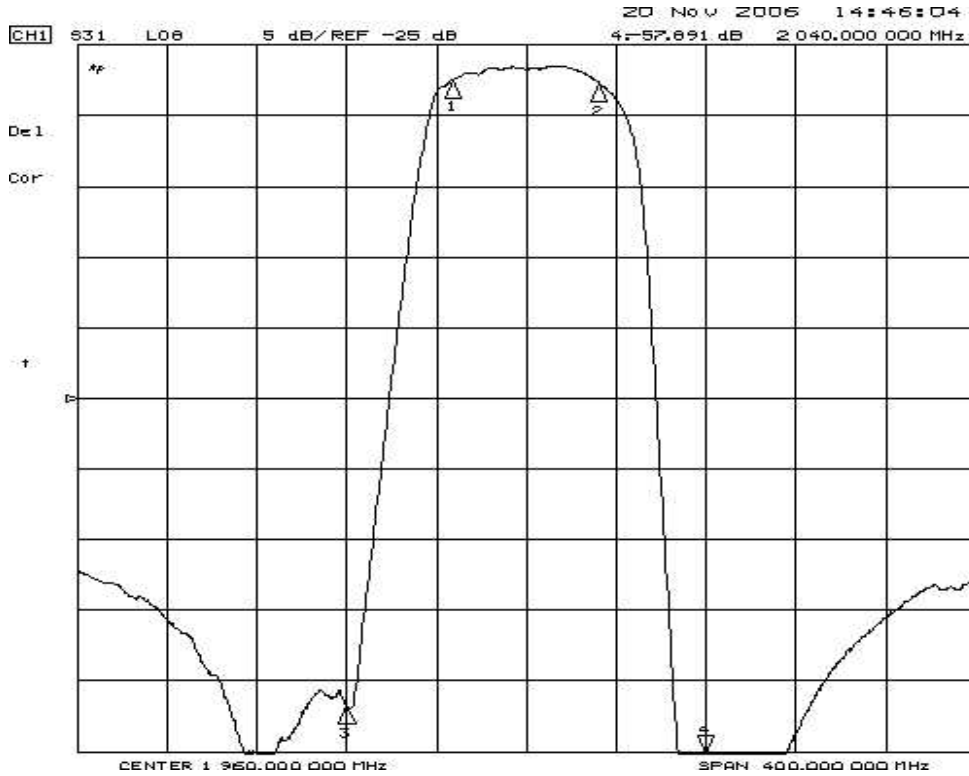


CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

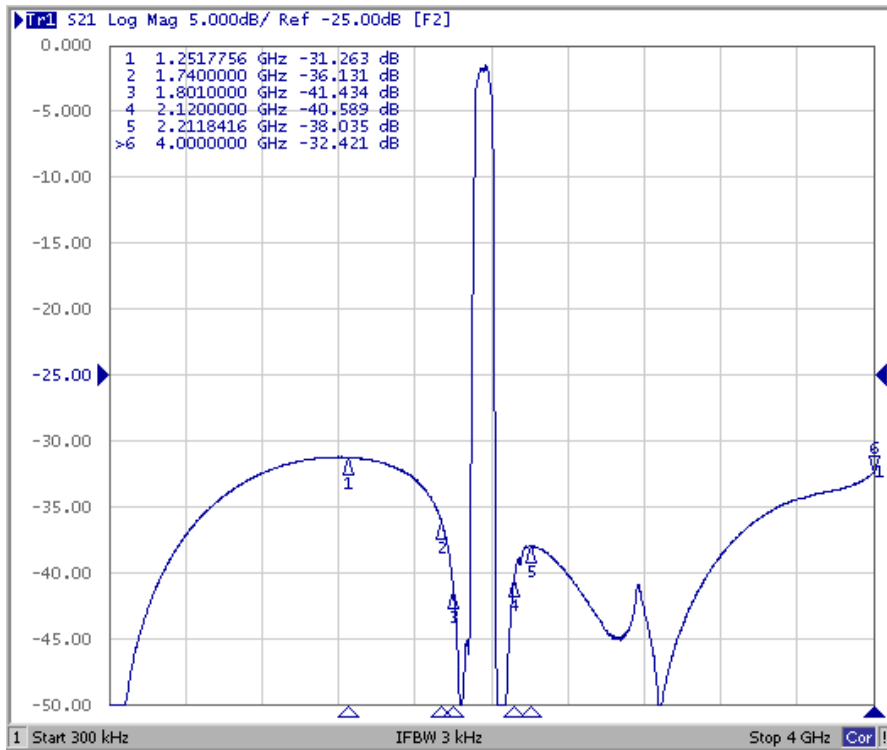
NOTES:

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.

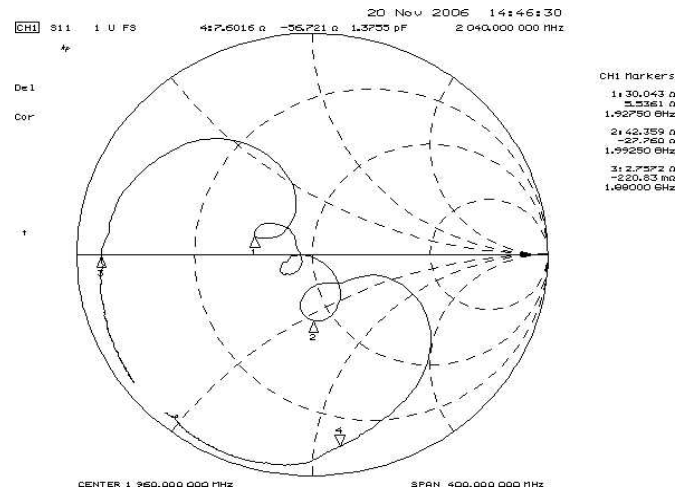
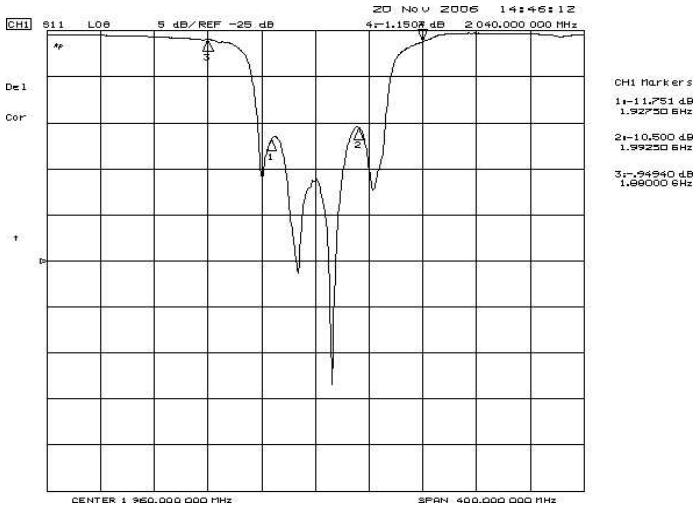
Filter Passband Response



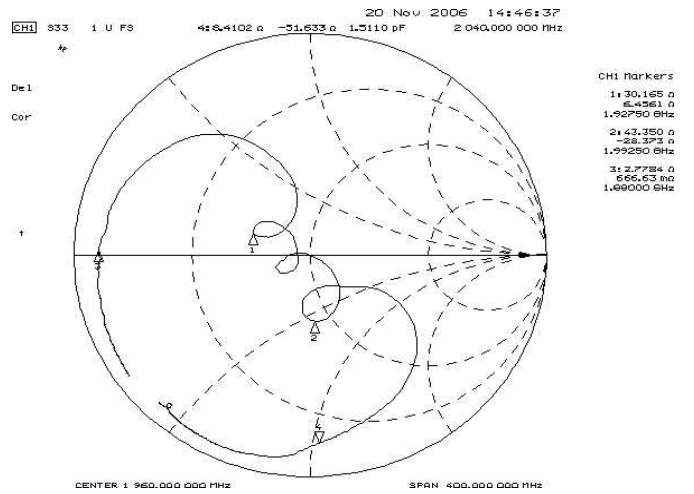
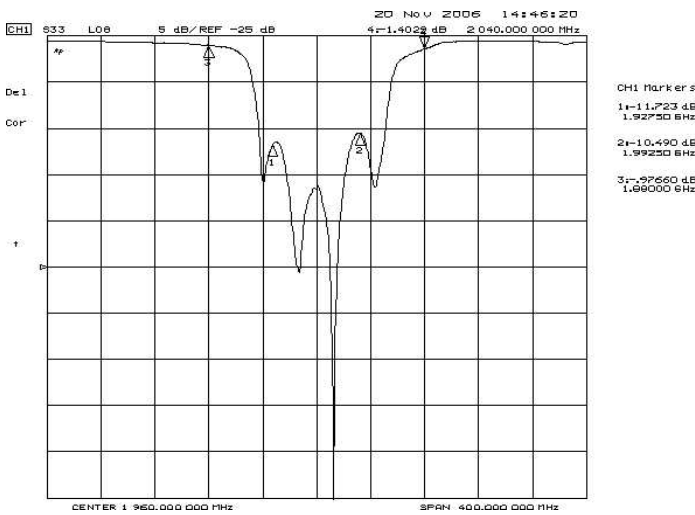
Filter Broadband Response



Filter Input VSWR and S₁₁ Plots

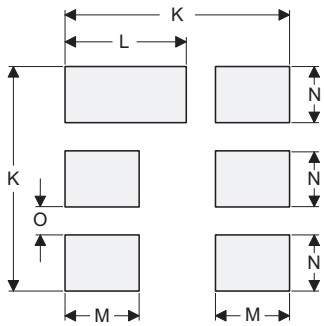
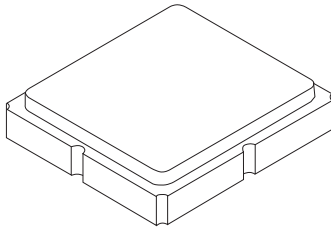


Filter Output VSWR and S₂₂ Plots



SM3030-6 Case

6-Terminal Ceramic Surface-Mount Case 3.0 X 3.0 mm Nominal Footprint



PCB Footprint Top View

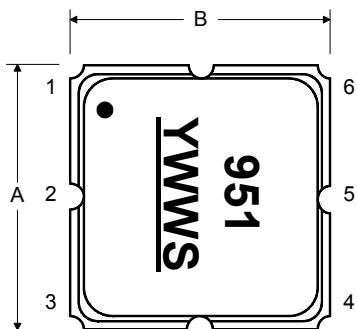
Case and PCB Footprint Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.87	3.00	3.13	0.113	0.118	0.123
B	2.87	3.00	3.13	0.113	0.118	0.123
C	1.12	1.25	1.38	0.044	0.049	0.054
D	0.77	0.90	1.03	0.030	0.035	0.040
E	2.67	2.80	2.93	0.105	0.110	0.115
F	1.47	1.60	1.73	0.058	0.063	0.068
G	0.72	0.85	0.98	0.028	0.033	0.038
H	1.37	1.50	1.63	0.054	0.059	0.064
I	0.47	0.60	0.73	0.019	0.024	0.029
J	1.17	1.30	1.43	0.046	0.051	0.056
K		3.20			0.126	
L		1.70			0.067	
M		1.05			0.041	
N		0.81			0.032	
O		0.38			0.015	

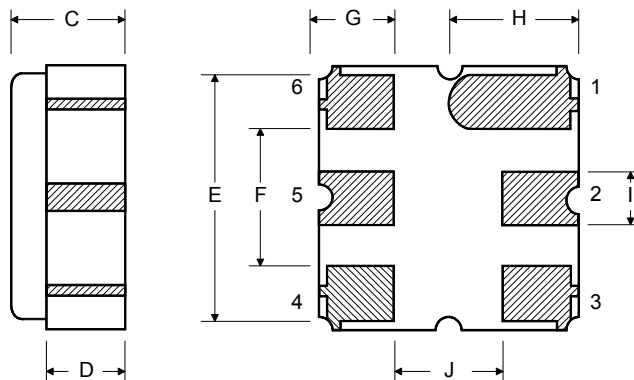
Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 μ m Gold over 1.27 to 8.89 μ m Nickel
Lid Plating	2.0 to 3.0 μ m Nickel
Body	Al ₂ O ₃ Ceramic
Pb Free	

TOP VIEW



BOTTOM VIEW



Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (10 seconds).
4. Time: 5 times maximum.

